CLAIMS

1. A polishing slurry for polishing a polishing object including a resin, wherein

the polishing slurry comprises alumina abrasives and silica abrasives,

the silica abrasives comprise aggregate particles composed of a plurality of primary particles of colloidal silica,

an average particle size of the primary particles is smaller than a median size of the alumina abrasives,

the average particle size of the primary particles is 40 nm or more, and a median size of the alumina abrasives is 120 nm or more.

2. The polishing slurry according to claim 1, having a pH of 7.0 or more and 12.0 or less.

3. The polishing slurry according to claim 1 or 2, wherein

a median size of the alumina abrasives is 300 nm or less, and a median size of the silica abrasives is 100 nm or more.